

Listing of Claims:

1 (canceled).

2 (canceled).

3 (canceled).

4 (canceled).

5 (canceled).

6 (canceled).

7 (canceled).

8 (canceled).

9 (canceled).

10 (canceled).

11 (canceled).

12 (canceled).

13 (canceled).

14 (canceled).

15(new). A probe card comprising:

- (a) a board including dielectric layer, said board defining an opening;
- (b) probe supported by said board, said probe including a probing element that extends through said opening;
- (c) a conductive pad supported by said board;
- (d) a conductive path electrically interconnecting said probing element and said pad; and

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(e) at least one of (1) a planar conductive member interposed within said board at a location at least partially directly underneath at least one of said conductive pad and said conductive path and (2) a conductive member positioned within said board and coextensive with a major portion of said board.

16(new). The probe card of claim 15 wherein said conductive path is a trace supported by the upper surface of said board.

17(new). The probe card of claim 15 wherein said conductive member is a trace interposed within said board.

18(new). The probe card of claim 15 wherein said conductive path includes a conductor of a cable.

19(new). The probe card of claim 15 wherein said conductive pad is a first conductive pad, said first conductive pad is part of a pad set that further includes a second conductive pad substantially electrically isolated from said first conductive pad.

20(new). The probe card of claim 19 wherein said conductive member is electrically connected to said second conductive pad.

21(new). The probe card of claim 19 wherein at least one of said first conductive pad and said second conductive pad is electrically connected to a surface conductive trace supported by said upper surface, said surface conductive trace encircling said pad set.

22(new). The probe of claim 21 wherein said surface conductive trace is electrically connected to said conductive member by a plurality of vias.

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23(new). The probe of claim 21 wherein said surface conductive trace is electrically connected to said conductive member by at least one plated trench.

24(new). The probe card of claim 15, wherein said conductive pad is a first conductive pad, further including a second conductive pad that is spaced apart from said first conductive pad, a trench breaching said upper surface between said first conductive pad and said conductive second pad.

25(new). The probe card of claim 15 further including an additional conductive member interposed within said probe card.

26(new). The probe card of claim 15 further including additional conductive pads and being adapted to mate to a pogo head.

27(new). The probe card of claim 15 wherein said conductive member is said at least partially directly underneath said conductive pad.

28(new). The probe card of claim 15 wherein said conductive member is said at least partially directly underneath said conductive path.